

ABSTRACT

~~It is an object of the present invention to provide a~~ A ceramic substrate for a semiconductor producing/examining device which has a high fracture toughness value, excellent thermal shock resistivity, high thermal conductivity and an excellent temperature rising and falling properties; ~~and is preferable as a hot plate, an electrostatic chuck, a wafer prober and the like~~ including the substrate; ~~A and a~~ ceramic substrate, for a semiconductor producing/examining device, having a conductor formed inside thereof or on the surface thereof ~~of the present invention is the ceramic substrate, wherein said ceramic substrate has been~~ which has been sintered such that a fractured section thereof exhibits intergranular fracture.